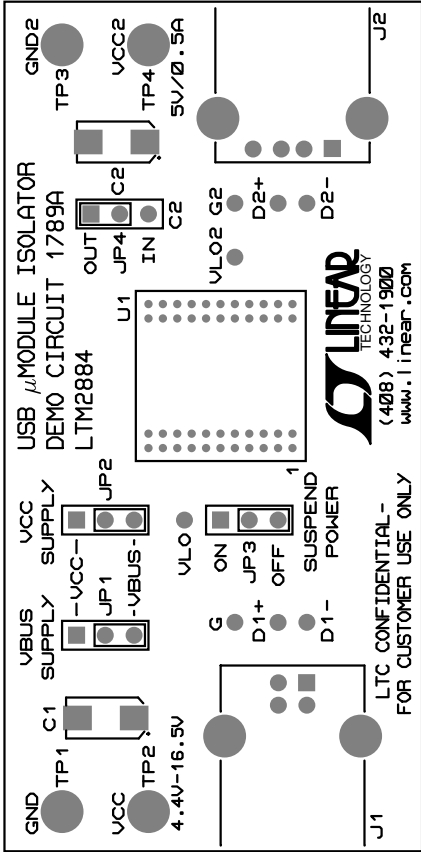



REVISION HISTORY				
ECO	REV	DESCRIPTION	APPROVED	DATE
-	3	3RD PROTOTYPE	KEITH B.	1-8-13

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610
2. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS
3. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD
4. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
5. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD
6. DO NOT APPLY ANY KIND OF ASSEMBLY OR QA STAMP TO ANY BOARD
7. INSTALL SHUNTS AS SHOWN



APPROVALS		<div><div>LINEAR TECHNOLOGY</div></div> <div>1630 McCarthy Blvd. Milpitas, CA 95035 Phone: (408) 432-1900 Fax: (408) 434-0507 www.linear.com</div> <div>LTC CONFIDENTIAL FOR CUSTOMER USE ONLY</div>		TITLE: ASSEMBLY DRAWING USB μMODULE ISOLATOR		SIZE		IC NO.		REV.	
PCB DES.	KEITH B.					N/A		LTM2884CY		3	
APP ENG.	KEITH B.							DEMO CIRCUIT 1789A			
SCALE = 1.5:1		DATE: Tuesday January 8, 2013		SHEET 1		OF 1					